

# PNP Transistor, 100 V, 3.0 A, Low V<sub>CE(sat)</sub>

# NSS1C300ET4G

**onsemi**'s  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

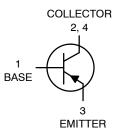
- Complement to NSS1C301ET4G
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Base Voltage	$V_{CBO}$	140	Vdc
Collector-Emitter Voltage	$V_{CEO}$	100	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	6.0	Vdc
Collector Current - Continuous	Ic	3.0	Adc
Collector Current - Peak	I <sub>CM</sub>	6.0	Adc
Base Current	Ι <sub>Β</sub>	0.5	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	33 0.26	W W/°C
Total Power Dissipation (Note 1) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	2.1 0.017	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# 100 VOLTS, 3.0 AMPS PNP LOW $V_{CE(sat)}$ TRANSISTOR





DPAK CASE 369C STYLE 1

#### **MARKING DIAGRAM**



Y = Year WW = Work Week 1C30E = Device Code G = Pb-Free

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS1C300ET4G	DPAK (Pb-Free)	2500/ Tape & Reel
NSV1C300ET4G	DPAK (Pb-Free)	2500/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

These ratings are applicable when surface mounted on the minimum pad sizes recommended.

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.8	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	59.5	°C/W

<sup>2.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-100	-	_	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-140	-	-	Vdc
Emitter – Base Breakdown Voltage (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-6.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -140 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>	_	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) $ \begin{aligned} &(I_C = -0.1 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -0.5 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -3.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{aligned} $	h <sub>FE</sub>	180 180 120 50	- - - -	- - 360 -	-
Collector – Emitter Saturation Voltage (Note 3) $ \begin{pmatrix} I_C = -0.1 \text{ A, } I_B = -10 \text{ mA} \end{pmatrix} $ $ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -3.0 \text{ A, } I_B = -0.300 \text{ A} \end{pmatrix} $	V <sub>CE(sat)</sub>	- - - -	- - -	-0.070 -0.150 -0.250 -0.400	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V <sub>BE(sat)</sub>	-	-	-1.0	V
Base – Emitter Turn–on Voltage (Note 3) (I <sub>C</sub> = –1.0 A, V <sub>CE</sub> = –2.0 V)	V <sub>BE(on)</sub>	_	-	-0.900	V
Cutoff Frequency ( $I_C = -500 \text{ mA}$ , $V_{CE} = -10 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	_	100	-	MHz
Input Capacitance (V <sub>EB</sub> = 5.0 V, f = 1.0 MHz)	Cibo	-	360	-	pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo	-	60	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulsed Condition: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2%.

#### **TYPICAL CHARACTERISTICS**

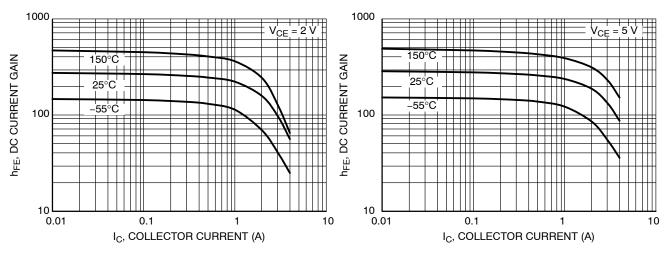


Figure 1. DC Current Gain

Figure 2. DC Current Gain

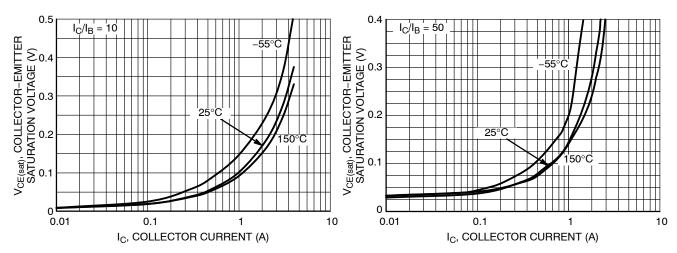


Figure 3. Collector-Emitter Saturation Voltage

Figure 4. Collector-Emitter Saturation Voltage

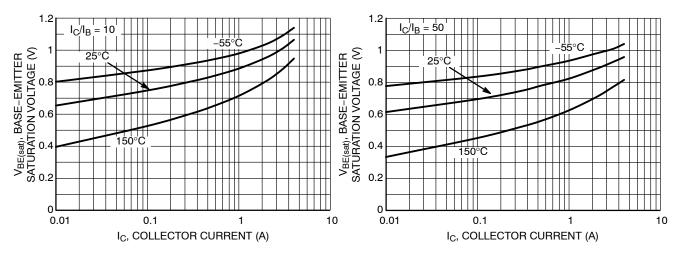


Figure 5. Base-Emitter Saturation Voltage

Figure 6. Base-Emitter Saturation Voltage

#### **TYPICAL CHARACTERISTICS**

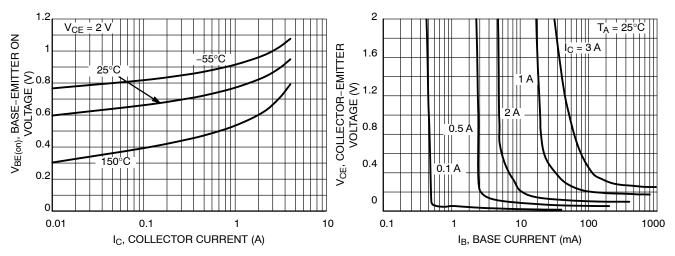


Figure 7. Base-Emitter On Voltage

Figure 8. Collector Saturation Region

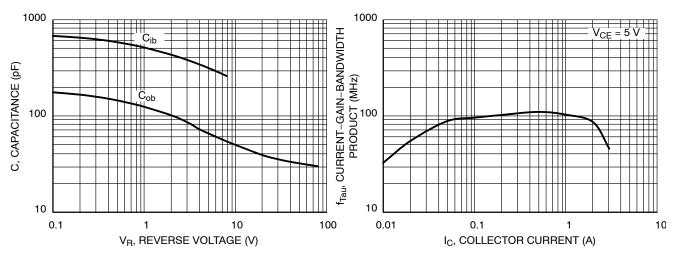


Figure 9. Capacitance

Figure 10. Current-Gain-Bandwidth Product

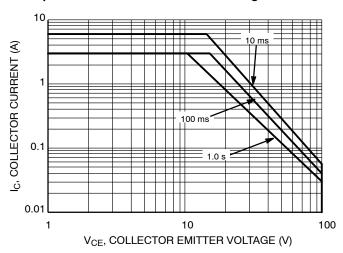


Figure 11. Safe Operating Area

# **TYPICAL CHARACTERISTICS**

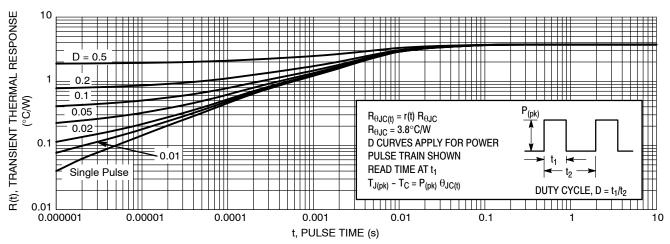


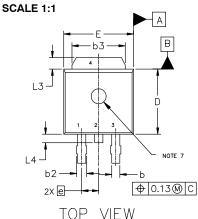
Figure 12. Typical Transient Thermal Response, Junction-to-Case

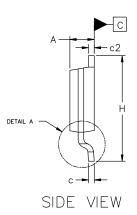




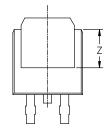
#### DPAK3 6.10x6.54x2.28, 2.29P CASE 369C **ISSUE J**

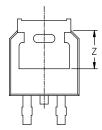
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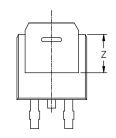


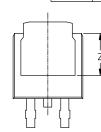


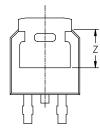
MILLIMETERS					
DIM	MIN	NOM	MAX		
А	2.18	2.28	2.38		
A1	0.00		0.13		
b	0.63	0.76	0.89		
b2	0.72	0.93	1.14		
b3	4.57	5.02	5.46		
С	0.46	0.54	0.61		
c2	0.46	0.54	0.61		
D	5.97	6.10	6.22		
E	6.35	6.54	6.73		
е	2.29 BSC				
Н	9.40	9.91	10.41		
L	1.40	1.59	1.78		
L1	2.90 REF				
L2	0.51 BSC				
L3	0.89		1.27		
L4			1.01		
Z	3.93				











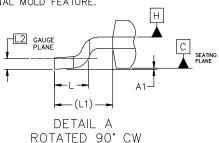
BOTTOM VIEW

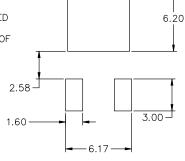
ALTERNATE CONSTRUCTIONS

#### NOTES:

- DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.

- CONTROLLING DIMENSION: MILLIMETERS.
  THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR
  BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H. OPTIONAL MOLD FEATURE.





-5.80

RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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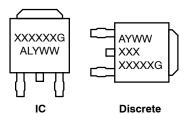
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#### DPAK3 6.10x6.54x2.28, 2.29P

CASE 369C **ISSUE J** 

**DATE 12 AUG 2025** 

#### **GENERIC MARKING DIAGRAM\***



XXXXXX = Device Code Α = Assembly Location = Wafer Lot L Υ = Year = Work Week ww = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:	STYLE 2:	STYLE 3:	ST	YLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. GATI	E PIN 1. AN	ODE P	IN 1. CATHODE	PIN 1. GATE
<ol><li>COLLE</li></ol>	CTOR 2. DRA	IN 2. CA	THODE	<ol><li>ANODE</li></ol>	2. ANODE
<ol><li>EMITTI</li></ol>	ER 3. SOU	RCE 3. AN	ODE	<ol><li>GATE</li></ol>	<ol><li>CATHODE</li></ol>
4. COLLE	CTOR 4. DRA	IN 4. CA	THODE	4. ANODE	4. ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2	STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE	3. RE	JODE NTHODE ESISTOR ADJUST NTHODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

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